Package Outline

**Exposed Diepad Dimensions**

<table>
<thead>
<tr>
<th>Package</th>
<th>Ex</th>
<th>Ey</th>
</tr>
</thead>
<tbody>
<tr>
<td>PG-DSO-36-24, -38, -41, -42, -50, -51, -53, -77, -79</td>
<td>7.0</td>
<td>5.1</td>
</tr>
<tr>
<td>PG-DSO-36-50, -80</td>
<td>6.0</td>
<td>5.4</td>
</tr>
<tr>
<td>PG-DSO-36-38, -75</td>
<td>5.2</td>
<td>4.6</td>
</tr>
</tbody>
</table>

Excluding the mold flash allowance of 0.3 max per side

Foot Print

Soldering Type: Reflow Soldering
Marking Layout

- Type code
- Manufacturer
- Date code (YYWW)
- Lot number
- Ball shape ejector mark
- Flat shape ejector mark

Tape and Reel

- Reel ø330 mm: 1,000 Pieces/Reel
- Reels/Box: 1

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